

IN THE CLAIMS

Please amend the claims as follows:

Claim 1 (previously presented): A multilayer printed circuit board comprising:

a substrate having an inner-layer conductor circuit formed inside the substrate and an outer-layer conductor circuit formed on the substrate;

a strain gauge formed inside the substrate and comprising a plurality of resin films and a resistive element held between the resin films, each of the resin films comprising one of polyimide and a thermoplastic resin; and

a plurality of electrodes electrically connected to the resistive element and exposed from one of the resin films; and

a plurality of viaholes electrically connected to the electrodes, respectively, through the one of the resin films.

Claim 2 (previously presented): The multilayer printed circuit board according to claim 1, wherein each of the resin films comprises one selected from the group consisting of polyimide, polyester, and polytetrafluoroethylene.

Claim 3 (original): The multilayer printed circuit board according to claim 1 or 2, wherein the viahole is filled with a conductive material.

Claim 4 (previously presented): The multilayer printed circuit board according to claim 1, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 5 (previously presented): A testing piece for a printed circuit board comprising:

a substrate having an inner-layer conductor circuit formed inside the substrate and an outer-layer conductor circuit formed on the substrate;

a strain gauge formed inside the substrate and comprising a plurality of resin films and a resistive element held between the resin films, each of the resin films comprising one of polyimide and a thermoplastic resin;

a plurality of electrodes electrically connected to the resistive element and exposed from one of the resin films; and

a plurality of viaholes electrically connected to the electrodes, respectively, through the one of the resin films.

Claim 6 (previously presented): The testing piece for the printed circuit board according to claim 5, wherein each of the resin films comprises one selected from polyimide, polyester, and polytetrafluoroethylene.

Claim 7 (original): The testing piece according to claim 5 or 6, wherein the viahole is filled with a conductive material.

Claim 8 (currently amended): The testing piece according to claim ~~[[1]]~~ 5, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 9 (previously presented): The multilayer printed circuit board according to claim 2, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 10 (previously presented): The multilayer printed circuit board according to claim 3, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 11 (previously presented): The multilayer printed circuit board according to claim 1, wherein the resistive element of the strain gauge comprises a metallic foil having a lattice shape.

Claim 12 (previously presented): The multilayer printed circuit board according to claim 1, wherein the resistive element of the strain gauge has a plurality of portions formed as the plurality of electrodes.

Claim 13 (previously presented): The multilayer printed circuit board according to claim 1, wherein the substrate comprises a plurality of insulating layers, and the inner-layer conductor circuit and the strain gauge are provided between the insulating layers.

Claim 14 (previously presented): The multilayer printed circuit board according to claim 1, wherein the resistive element is laminated between the resin films by hot-press such that the resistive element is held tight between the resin films.

Claim 15 (previously presented): The test piece according to claim 6, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 16 (previously presented): The test piece according to claim 7, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 17 (previously presented): The multilayer printed circuit board according to claim 5, wherein the resistive element of the strain gauge comprises a metallic foil having a lattice shape.

Claim 18 (previously presented): The multilayer printed circuit board according to claim 5, wherein the resistive element of the strain gauge has a plurality of portions formed as the plurality of electrodes.

Claim 19 (previously presented): The multilayer printed circuit board according to claim 5, wherein the substrate comprises a plurality of insulating layers, and the inner-layer conductor circuit and the strain gauge are provided between the insulating layers.

Claim 20 (previously presented): The multilayer printed circuit board according to claim 5, wherein the resistive element is laminated between the resin films by hot-press such that the resistive element is held tight between the resin films.